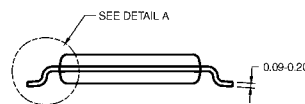
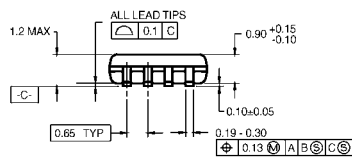
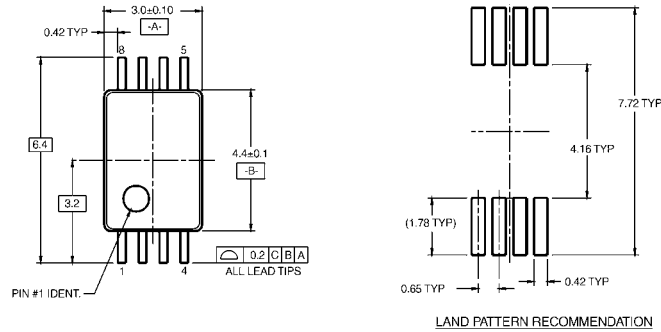


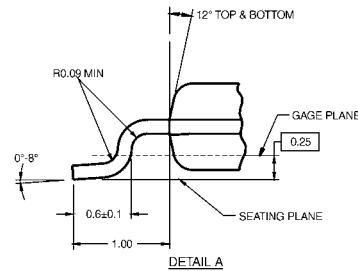
Package MTC08



DIMENSIONS ARE IN MILLIMETERS

- NOTES:
- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.
 - DIMENSIONS ARE IN MILLIMETERS.
 - DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC08RevA1



**8-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC08**

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- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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